

HOLDING SURFACE MAINTAINING METHOD

ABSTRACT

Whether or not there is an abnormality in a holding surface is determined on the basis of a difference between initial holding surface height data as the height of the holding surface immediately after a holding surface grinding step and interim holding surface height data as the height of the holding surface after a grinding step and a holding surface cleaning step are performed a plurality of times. Hence, a wafer does not need to be ground in order to determine whether or not there is an abnormality in the holding surface. An amount of consumption of wafers can therefore be suppressed.

[FIG. 1]